

PROCESS FOR BONDING AND TRANSFERRING A LAYER

ABSTRACT

The invention relates to a process for bonding and transferring a layer of material (12) onto a receiver substrate (2), used during the fabrication of a substrate intended notably for applications in the fields of electronics, optics or opto-electronics.

This process comprises the following steps:

- bond by molecular adhesion the said receiver substrate (2) and a donor substrate (1),
- apply heat treatment to the aforementioned stack in order to consolidate the bonding interface (5),
- thin the donor substrate (1) by grinding,
- perform an annular trimming of the donor substrate (1) and of a part of the receiver substrate (2),
- after the aforementioned steps, carry out a chemical etching step of the exposed surface of the remaining part of the donor substrate (1) and of the exposed surface of the receiver substrate (2).

FIG. 1E